

EDQP200-2DPx

200G QSFP56 to 2DSFP Direct Attach Cable (DAC)

PRODUCT FEATURES

- **Compatible with IEEE 802.3cd**
- **Supports aggregate data rates of 200Gbps(PAM4)**
- **Optimized construction to minimize insertion loss and cross talk**
- **Backward compatible with existing QSFP+ connectors and cages**
- **Pull-to-release slide latch design**
- **26AWG through 30AWG cable**
- **Straight and break out assembly configurations available**
- **Customized cable braid termination limits EMI radiation**
- **Customizable EEPROM mapping for cable signature**
- **RoHS compliant**

APPLICATIONS

- **Switches,servers and routers**
- **Data Center networks**
- **Storage area networks**
- **High performance computing**
- **Telecommunication and wireless infrastructure**
- **Medical diagnostics and networking**
- **Test and measurement equipment**

DESCRIPTIONS

QSFP56 passive copper cable assembly feature eight differential copper pairs, providing four data transmission channels at speeds up to 56Gbps(PAM4) per channel and meets 200G Ethernet and InfiniBand Data Rate(EDR) requirements. Available in a broad range of wire gauges—from 26AWG through 30AWG—this 200G copper cable assembly features low insertion loss and low cross talk.

DSFP Direct Attach Cables Latching mechanism compatible with SFP+. Various choices of wire gauge are available from 30 to 26 AWG with various choices of cable length (up to 3m).

Ordering Information

Part No.	Description
EDQP200-2DPx	200G QSFP56 to 2DSFP Direct Attach Cable xM

Notes:

- where "x" denotes cable length in meters. Examples are as follows:
- x = 1 for 1m

Wire gauge Information

Part Number	EDQP200-2DPx		
Length (meter)	1	2	3
Wire gauge (AWG)	30	28	26

High Speed Characteristics

Parameter	Symbol	Min	Typical	Max	Unit	Note
Differential Impedance	TDR	90	100	110	Ω	
Insertion loss	SDD21	-16.06			dB	At 13.28 GHz
Differential Return Loss	SDD11			See 1	dB	At 0.05 to 4.1 GHz
	SDD22			See 2	dB	At 4.1 to 19 GHz
Common-mode to common-mode output return loss	SCC11 SCC22			-2	dB	At 0.2 to 19 GHz
Differential to common-mode return loss	SCD11 SCD22			See 3	dB	At 0.01 to 12.89 GHz
				See 4		At 12.89 to 19 GHz
Differential to common Mode Conversion Loss	SCD21-IL			-10	dB	At 0.01 to 12.89 GHz
				See 5		At 12.89 to 15.7 GHz
				-6.3		At 15.7 to 19 GHz

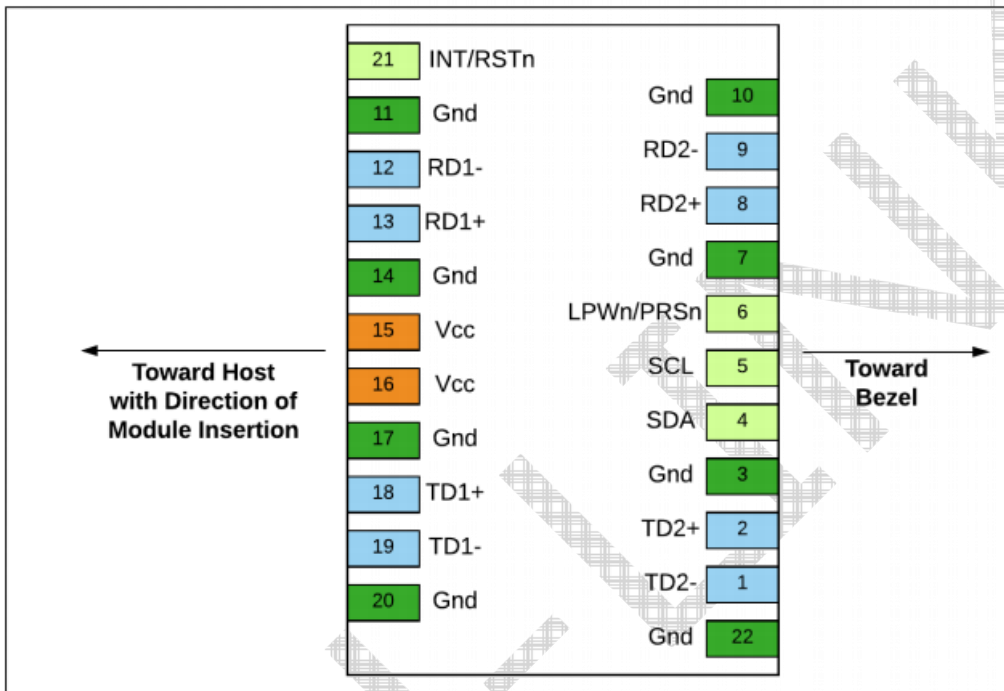
Notes:

- Reflection Coefficient given by equation $SDD11(\text{dB}) < -16.5 + 2 \times \text{SQRT}(f)$, with f in GHz
- Reflection Coefficient given by equation $SDD11(\text{dB}) < -10.66 + 14 \times \log_{10}(f/5.5)$, with f in GHz

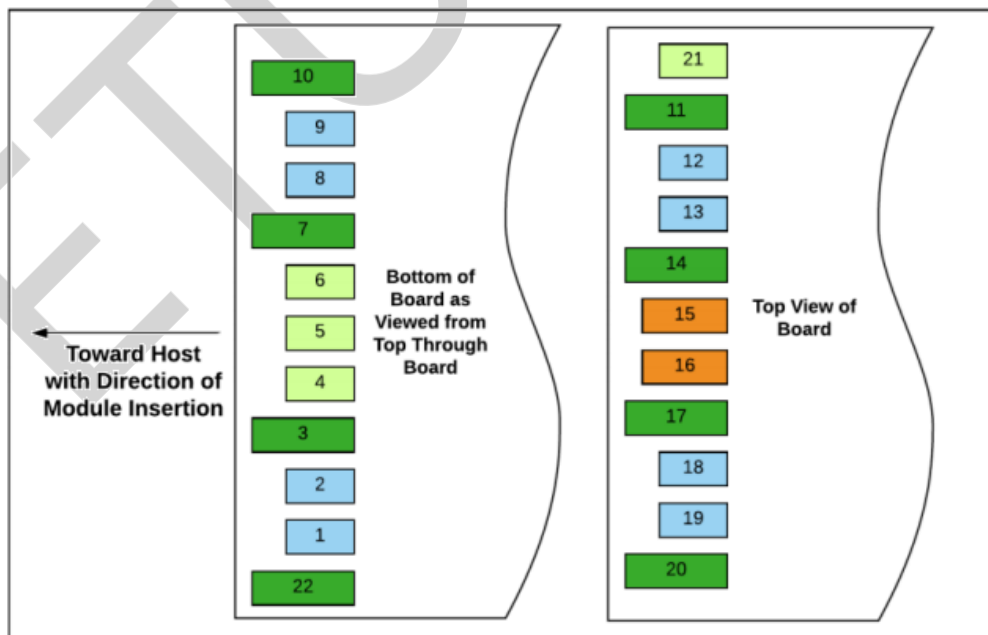
3. Reflection Coefficient given by equation $SCD11(dB) < -22 + (20/25.78)*f$, with f in GHz
4. Reflection Coefficient given by equation $SCD11(dB) < -15 + (6/25.78)*f$, with f in GHz
5. Reflection Coefficient given by equation $SCD21(dB) < -27 + (29/22)*f$, with f in GHz

Pin Diagram

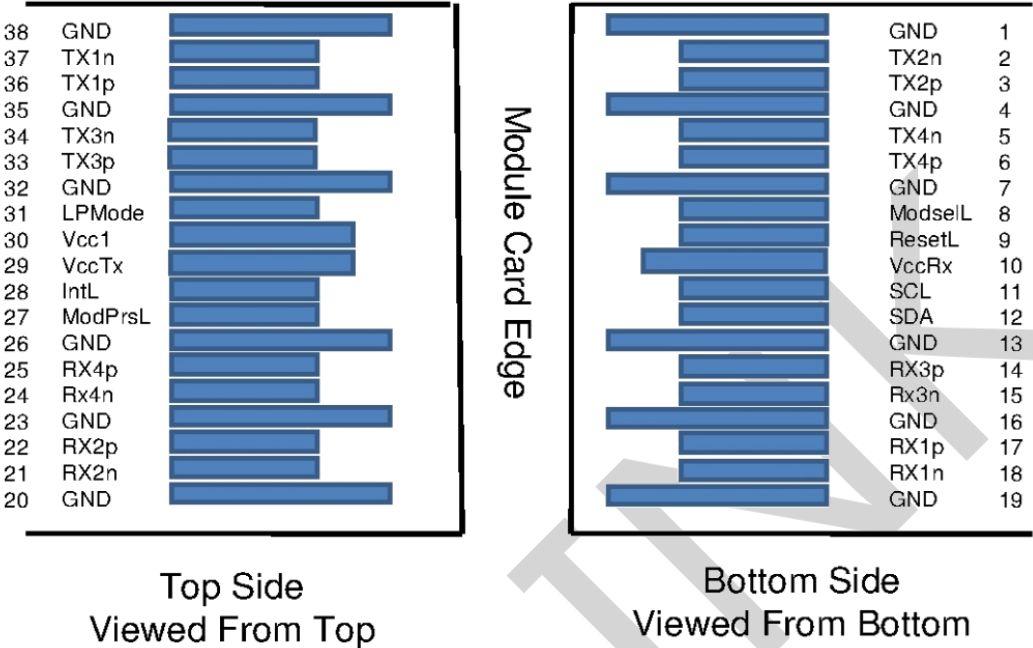
DSFP Host PCB pad assignment top view



DSFP module contact assignment



Pin arrangement



Pin Definitions

The DSFP connector is a 0.8 mm pitch 22 contacts improved connector compatible to SFP+ 20 contacts connector.

Pin	Logic	Symbol	Name/Description	Notes
1	CML-I	TD2-	Transmitter Inverted Data Input Lane 2	
2	CML-I	TD2+	Transmitter Non-Inverted Data Input Lane 2	
3		Gnd	Module Ground	5
4	LVTTL-I/O	SDA	2-wire Serial Interface Data Line	3
5	LVTTL-I/O	SCL	2-wire Serial Interface Clock	3
6	Multilevel-I/O	LPWn/PRSn	Low Power Mode/ Module Present (Mod_Abs)	
7		Gnd	Module Ground	5
8	CML-O	RD2+	Receiver Non-Inverted Data Output Lane 2	
9	CML-O	RD2-	Receiver Inverted Data Output Lane 2	
10		Gnd	Module Ground	5
11		Gnd	Module Ground	5
12	CML-O	RD1-	Receiver Inverted Data Output Lane 1	4
13	CML-O	RD1+	Receiver Non-Inverted Data Output Lane 1	4
14		Gnd	Module Ground	5
15		Vcc	Module 3.3 V Supply	
16		Vcc	Module 3.3 V Supply	
17		Gnd	Module Ground	5

18	CML-I	TD1+	Transmitter Non-Inverted Data Input Lane 1	4
19	CML-I	TD1-	Transmitter Inverted Data Input Lane 1	4
20		Gnd	Module Ground	5
21	Multilevel-I/O	INT/RSTn	Dual Function Module Interrupt and Reset Pin	
22		Gnd	Module Ground	5

Notes:

1. Labeling as inputs (I) and outputs (O) are from the perspective of the module.
2. The case makes electrical contact to the cage before any of the board edge contacts are made.
3. See 4.4 the 2-wire specifications.
4. Backward compatible with SFF-8431 SFI interface.
5. The module ground contacts Gnd recommended to be isolated from the module case by offering flexibility in the host EMI control strategy.

QSFP28 Pin Function Definition

Pin	Logic	Symbol	Description
1		GND	Ground
2	CML-I	Tx2n	Transmitter Inverted Data Input
3	CML-I	Tx2p	Transmitter Non-Inverted Data Input
4		GND	Ground
5	CML-I	Tx4n	Transmitter Inverted Data Input
6	CML-I	Tx4p	Transmitter Non-Inverted Data Input
7		GND	Ground
8	LVTTL-I	ModSelL	Module Select
9	LVTTL-I	ResetL	Module Reset
10		Vcc Rx	+3.3V Power Supply Receiver
11	LVC MOS-	SCL	2-wire serial interface clock
	I/O		
12	LVC MOS-	SDA	2-wire serial interface data
	I/O		
13		GND	Ground
14	CML-O	Rx3p	Receiver Non-Inverted Data Output
15	CML-O	Rx3n	Receiver Inverted Data Output
16		GND	Ground
17	CML-O	Rx1p	Receiver Non-Inverted Data Output
18	CML-O	Rx1n	Receiver Inverted Data Output
19		GND	Ground
20		GND	Ground
21	CML-O	Rx2n	Receiver Inverted Data Output
22	CML-O	Rx2p	Receiver Non-Inverted Data Output
23		GND	Ground
24	CML-O	Rx4n	Receiver Inverted Data Output
25	CML-O	Rx4p	Receiver Non-Inverted Data Output
26		GND	Ground
27	LVTTL-O	ModPrsL	Module Present

28	LVTTTL-O	IntL	Interrupt
29		Vcc Tx	+3.3V Power supply transmitter
30		Vcc1	+3.3V Power supply
31	LVTTTL-I	LPMode	Low Power Mode
32		GND	Ground
33	CML-I	Tx3p	Transmitter Non-Inverted Data Input
34	CML-I	Tx3n	Transmitter Inverted Data Input
35		GND	Ground
36	CML-I	Tx1p	Transmitter Non-Inverted Data Input
37	CML-I	Tx1n	Transmitter Inverted Data Input
38		GND	Ground

Recommended Interface Circuit

QSFP28

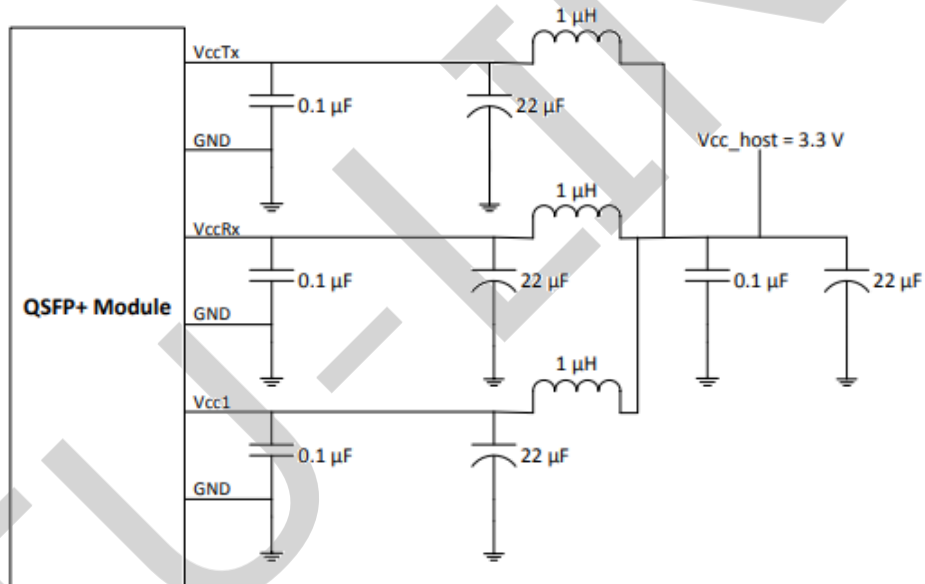
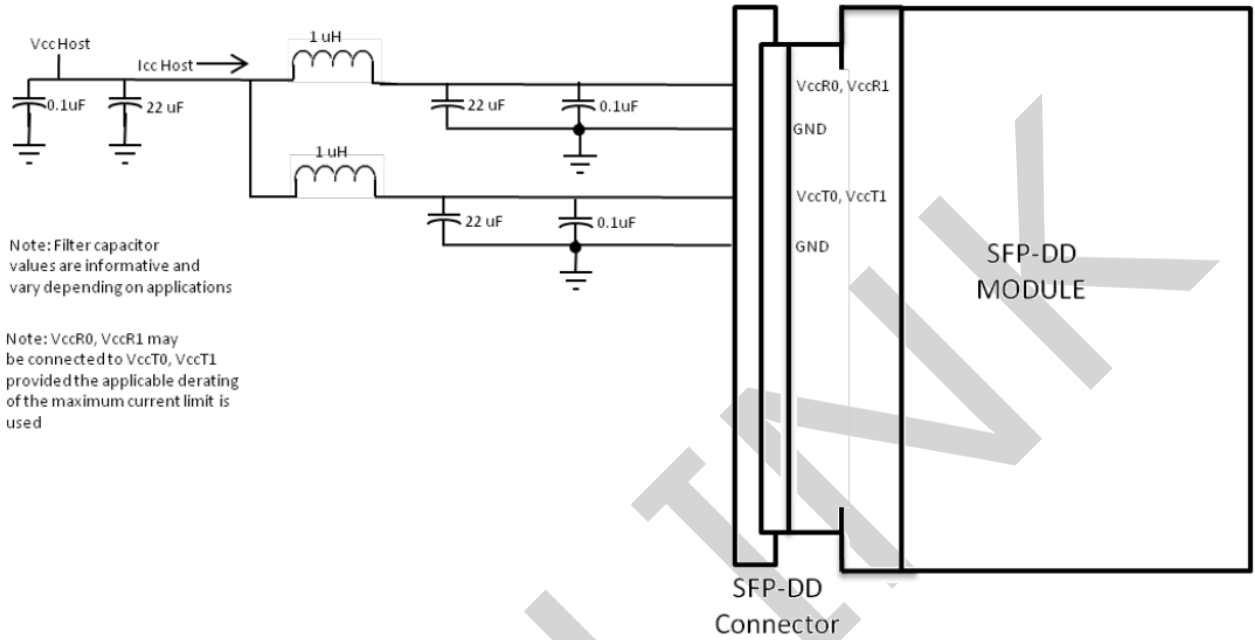


FIGURE 5-4 RECOMMENDED HOST BOARD POWER SUPPLY FILTERING

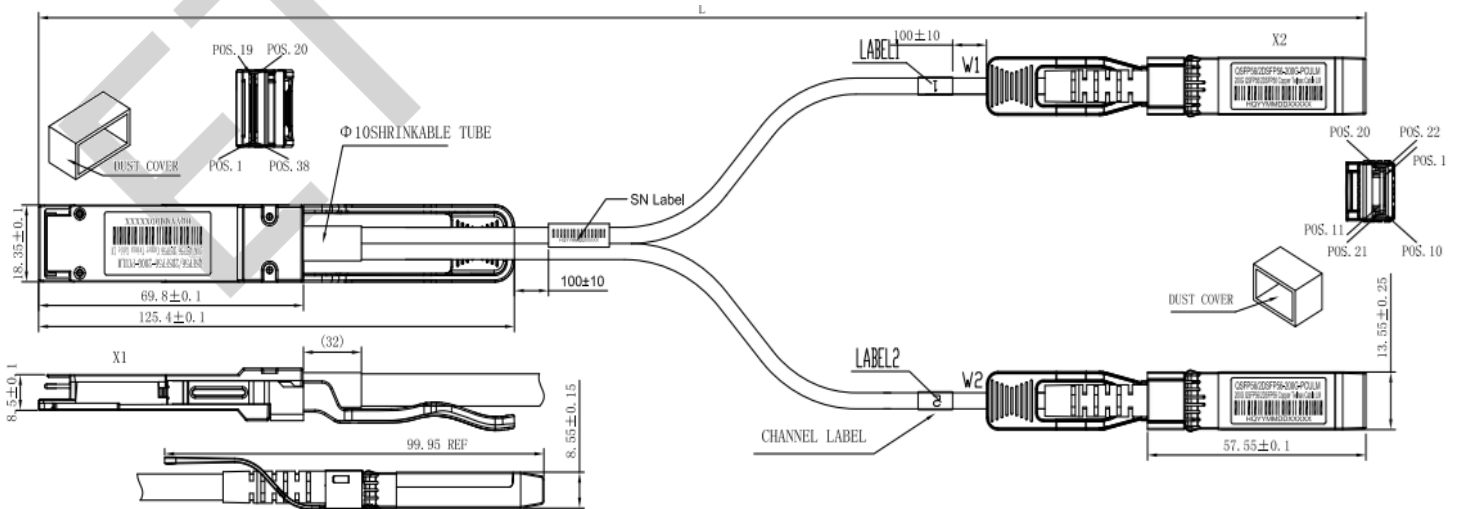
SFP-DD

SFP-DD Rev 2.1



Mechanical Diagram

The connector is compatible with the DSFP and SFF-8661 specification.



Revision History

Version No.	Date	Description
1.0	May 18, 2022	Preliminary datasheet
1.1	Aug 25, 2024	Format change

Company: ETU-Link Technology Co., LTD

Production base: Right side of 3rd floor, No. 102 building, Longguan expressway, Dalang street, Longhua District, Shenzhen city, Guangdong Province, China 518109

R&D base: Floor 4, Building 4, Nanshan Yungu Phase LI, Taoyuan Community, Xili Street, Nanshan District, Shenzhen

Tel: +86-755 2328 4603

Addresses and phone number also have been listed at www.etulinktechnology.com.

Please e-mail us at sales@etulinktechnology.com or call us for assistance.